30 April 2003

09/762,582

L Number	Hits	Search Text	DB	Time stamp
-	0	762582.apn.	USPAT;	2003/04/29
			US-PGPUB;	11:23
		·	EPO; JPO;	
	;		DERWENT	
-	9	(("5116430") or ("3716462") or ("3930963")).PN.	USPAT;	2003/04/29
			US-PGPUB;	13:53
			EPO; JPO;	
•		• •	DERWENT	
_	1	jp-51149131-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	12:13
			EPO; JPO;	
		. *	DERWENT	
_	2	4163705.pn.	USPAT;	2003/04/29
	_	,	US-PGPUB;	12:13
			EPO; JPO;	,
1			DERWENT	, .
	7	(("5849171") or ("4430173") or ("5433840")).PN.	USPAT;	2003/04/30
	,	((30 15171) 61 (1 186176) 61 (5 1868 18))	US-PGPUB;	09:43
	ļ		EPO; JPO;	03110
			DERWENT	
•	2657	204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
- .	2037	204/190,212,232,242,273,273.1.003.	US-PGPUB;	13:55
			EPO; JPO;	13.33
			DERWENT	
	. 772	204/224r.ccls. /	USPAT;	2003/04/29
•	, 773	204/224r.ccis.	US-PGPUB;	13:55
			1	13.55
			EPO; JPO;	÷
	2272	004/400 040 000 040 070 075 4 1, 204/204	DERWENT	2002/04/20
- 0)	3270	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/29
		,	US-PGPUB;	13:55
			EPO; JPO;	-
			DERWENT	0000/04/00
-	35	(204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
1		204/224r.ccls.) and electroless and (electrolytic or	US-PGPUB;	14:04
		electroplating) and robot	EPO; JPO;	
			DERWENT	
-	58753	204/\$.ccls.	USPAT;	2003/04/29
			US-PGPUB;	14:04
			EPO; JPO;	
			DERWENT	
-	55	204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot	US-PGPUB;	14:04
			EPO; JPO;	
			DERWENT	
-	20	(204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot) not	US-PGPUB;	14:14
		((204/198,212,232,242,273,275.1.ccls.	EPO; JPO;	
	-	204/224r.ccls.) and electroless and (electrolytic or	DERWENT	
		electroplating) and robot)		
-	2	6080291.pn.	USPAT;	2003/04/29
			US-PGPUB;	14:07
			EPO; JPO;	
	Ι.		DERWENT	

-	813	204/\$.ccls. and (robot or robotic)	USPAT;	2003/04/29
			US-PGPUB;	14:14
	•	·	EPO; JPO;	
			DERWENT	
_	78	(204/\$.ccls. and (robot or robotic)) and electroless	USPAT;	2003/04/29
_	, ,	(20 17 \$1.0010. dilla (10001 01 1000110)) dilla 0100110100	US-PGPUB;	14:15
			EPO; JPO;	
			DERWENT	
	81	204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
-	01	1	US-PGPUB;	14:16
		(transfer adj unit) or (transfer adj device) or		14.10
		(transfer adj arm))	EPO; JPO;	
		(004/4:1	DERWENT	2002/04/20
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:17
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	
		and (electrolytic or electroplating) and robot) not	DERWENT	
		((204/\$.ccls. and electroless and (electrolytic or		
	1	electroplating) and robot) not		
		((204/198,212,232,242,273,275.1.ccls.		
		204/224r.ccls.) and electroless and (electrolytic or		
9		electroplating) and robot))		
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:33
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	
	·	and (electrolytic or electroplating) and robot) not	DERWENT	*
		((204/198,212,232,242,273,275.1.ccls.		
		204/224r.ccls.) and electroless and (electrolytic or		
		electroplating) and robot)		
	2	6197181.pn.	USPAT;	2003/04/29
		0197101.pm	US-PGPUB:	14:21
			EPO; JPO;	
	1	,	DERWENT	
	2	jp-56158424-\$.did.	USPAT;	2003/04/29
-		- 1p-30130424-φ.did.	US-PGPUB;	14:34
		· '	EPO; JPO;	14.54
			DERWENT	
		1003 040305 ND 481		2003/04/20
_	1	1982-04830E.NRAN.	DERWENT	2003/04/29
		:- 05311404	LICDAT	14:33 2003/04/29
-	2	jp-05311496-\$.did.	USPAT;	
	•		US-PGPUB;	14:35
	P. 2		EPO; JPO;	
			DERWENT	2002 (24 (22
-	2	jp-07193214-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:37
		,	EPO; JPO;	
			DERWENT	
-	1	1995-217803.NRAN.	DERWENT	2003/04/29
		• .		14:37
-	2	jp-02000341-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:39
		·	EPO; JPO;	
		•	DERWENT	
-	1	1990-047945.NRAN.	DERWENT	2003/04/29
				14:39

- 2 j	p-56161221-\$.did.	USPAT;	2003/04/29
		US-PGPUB;	14:42
	•	EPO; JPO;	
		DERWENT	
- 1 j	p-51149131 - \$.did.	USPAT;	2003/04/29
		US-PGPUB;	14:43
	•	EPO; JPO;	
		DERWENT	
- 1 1	976-75692X,NRAN,	DERWENT	2003/04/29
1.1	970-7309EX.INRAIN.	DERVEINI	14:42
- 2 i	03144400 ¢ 4:4	USPAT;	2003/04/29
- 2 J	p-03146698-\$.did.		·
		US-PGPUB;	14:44
		EPO; JPO;	*
		DERWENT	
- 2 j	p-05098500-\$.did.	USPAT;	2003/04/29
·		US-PGPUB;	14:45
		EPO; JPO;	
		DERWENT	
- 2 j	p-62235499-\$.did.	USPAT;	2003/04/29
		US-PGPUB;	14:46
		EPO; JPO;	
		DERWENT	
- 2 i	p-63026400-\$.did.	USPAT;	2003/04/29
- 31	,	US-PGPUB;	14:50
		EPO; JPO;	
		DERWENT	• •
- 1 1	997wo-??22733.ap,prai.	USPAT;	2003/04/29
	997 WO-??227 33.ap,pi di.	US-PGPUB;	14:51
			14.01
	•,	EPO; JPO;	
	22722 4 114	DERWENT	2002/04/20
- 0 w	o-22733-\$.did.	USPAT;	2003/04/29
		US-PGPUB;	14:52
		EPO; JPO;	
		DERWENT	
- 0 w	o-00022733-\$.did.	USPAT;	2003/04/29
	·	US-PGPUB;	14:52
	•	EPO; JPO;	
	*	DERWENT	
- 0 w	o-97022733-\$.did.	USPAT;	2003/04/29
		US-PGPUB;	14:52
	•	EPO; JPO;	
		DERWENT	•
- 58753 2	04/\$.ccls.	USPAT;	2003/04/29
	· · · · · · · · · · · · · · · · · · ·	US-PGPUB;	15:10
	,	EPO; JPO;	
		DERWENT	
- 708 2	04/\$ sele and (alactrologe and (alactrolytic as	USPAT;	2003/04/29
1 •	04/\$.ccls. and (electroless and (electrolytic or		1
e	lectroplating or electroplate))	US-PGPUB;	15:11
	ļ	EPO; JPO;	
		DERWENT	
1 1 1	204/\$.ccls. and (electroless and (electrolytic or	USPAT;	2003/04/29
1 ' 1	lectroplating or electroplate))) and (robot or robotic	US-PGPUB;	15:12
0	r ((transfer or conveyance or conveyor) adj (means!	EPO; JPO;	
, ,	r unit or device or system or arm)))	DERWENT	



	•	160054	205/\$.ccls. or 427/\$.ccls.	USPAT;	2003/04/29
			· .	US-PGPUB;	15:47
				EPO; JPO;	
			·	DERWENT	
	-	14963	(205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
	•	-	wafer)	US-PGPUB;	15:48
				EPO; JPO;	
	•			DERWENT	
	_	759	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
			wafer)) and electroless and (electroplating or	US-PGPUB;	15:49
			electroplated or electroplate or electrolytic or	EPO; JPO;	
		"	electrochemically)	DERWENT	
I	-	54	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
			wafer)) and (electroless near2 (tank or bath)) and	US-PGPUB;	15:49
			((electroplating or electroplated or electroplate or	EPO; JPO;	120112
۱			electrolytic or electrochemically) near2 (tank or	DERWENT	
	-		bath))		
1	-	60	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
	,		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:54
			chamber)) and ((electroplating or electroplated or	EPO; JPO;	15.54
			electroplate or electrolytic or electrochemically)	DERWENT	
-			near2 (tank or bath or chamber))	DERVENT	
	_	7	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		/	wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:51
			chamber)) and ((electroplating or electroplated or	EPO; JPO;	15.51
l			electroplate or electrolytic or electrochemically)	DERWENT	
			near2 (tank or bath or chamber))) and (robot or	DERWEINT	
	•		robotic or ((transfer or conveyor or conveyance) near		0
	-		(arm or unit or device or means!)))	-	
		29	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
	_		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:55
				EPO; JPO;	15.55
			chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically)	DERWENT	
	•		near2 (tank or bath or chamber))) and ((copper adj	DERWEINT	
-					1,0
		8	sulfate) or "Cuso.sub.4") (("5500315") or ("5310580") or ("5389496") or	LICDAT	2002/04/20
	-	, 0		USPAT; US-PGPUB;	2003/04/30
			("5139818")) PN		08:52
	•			EPO; JPO;	
			alastos and ((samman adi adilésta) adilestas a la 400	DERWENT	2003/04/20
	•	0	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
			and ((chlorine or chloride) adj ions) and (sufuric adj	US-PGPUB;	08:54
			acid)	EPO; JPO;	
			alianta da and Mannan alia 10 to North Carlo	DERWENT	2002/04/20
l	-	1896	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
١				US-PGPUB;	08:54
				EPO; JPO;	
				DERWENT	000015115
	-	1019	(electroless and ((copper adj sulfate) or "cuso.sub.4"))	USPAT;	2003/04/30
		_	and (sulfuric adj acid)	US-PGPUB;	08:54
		'		EPO; JPO;	
L				DERWENT	0



. 11-21			1110017	0000/04/00
-	220	((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	,
		ppg!)	DERWENT.	
-	52	(((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
•		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	*
		ppg!)) and sulfur and nitrogen	DERWENT	
•	51	((((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	09:06
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	
		ppg!)) and sulfur and nitrogen) and (chlorine or	DERWENT	
•		chloride)		
-	0	uk-1222969-\$.did.	USPAT;	2003/04/30
		*	US-PGPUB;	09:07
			EPO; JPO;	·
			DERWENT	
	1	gb-1222969-\$.did.	USPAT;	2003/04/30
·	1		US-PGPUB;	09:11
			EPO; JPO;	
6. · ·			DERWENT	
	59	(204/\$.ccis. or 205/\$.ccis.) and bubble and (pressure	USPAT;	2003/04/30
٠.		near (module or modulation or modulating or pulse or	US-PGPUB;	10:01
	*	pulsating or pulsed or pulsing or pulsated or varied or	EPO; JPO;	10.01
		variable or cyclical))	DERWENT	
_*	8	(204/\$.ccls. or 205/\$.ccls.) and (bubble with	USPAT;	2003/04/30
•		(pressure near (module or modulation or modulating or	US-PGPUB;	10:09
		pulse or pulsating or pulsed or pulsing or pulsated or	ÉPO; JPO;	10.05
Ť.		varied or variable or cyclical)))	DERWENT	
	111	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same	USPAT;	2003/04/30
•	111	(pressure near (module or modulation or modulating or	US-PGPUB;	10:20
		1 3	1	10.20
		pulse or pulsating or pulsed or pulsing or pulsated or	EPO; JPO;	
	102	varied or variable or cyclical)))	DERWENT	2002/04/20
•	102	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same	USPAT;	2003/04/30
		(pressure near (modulate or modulation or modulating	US-PGPUB;	13:38
•		or pulse or pulsating or pulsed or pulsing or pulsated	EPO; JPO;	
	04500	or varied or variable or cyclical)))	DERWENT	2002 (0 1 /22
•	21529	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
÷ ,		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:19
		(circuit board))	EPO; JPO;	
			DERWENT	
•	2051	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:19
		(circuit board))) and bubble	EPO; JPO;	
			DERWENT	
-	241	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:20
	4	(circuit board))) and (bubble with pressure)	EPO; JPO;	
		* * *	DERWENT	

	69	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
	0)	wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:21
		(circuit board))) and ((bubble or gas) same (pressure	EPO; JPO;	
		near (modulate or modulation or modulating or pulse or	DERWENT	
	,	1	DERWEINT	•.
	-	pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))		
-	. 2	5865894.pn.	USPAT;	2003/04/30
			US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT	
-	83136	204/\$.ccls. or 205/\$.ccls.	USPAT;	2003/04/30
			US-PGPUB;	13:41
			EPO; JPO;	
·			DERWENT	
_	18	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
		(bubbles with (sonic or ultrasonic or megasonic))	US-PGPUB;	13:45
			EPO; JPO;	
	•		DERWENT	
_	2	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
	-	(bubbles with (sonic or ultrasonic or megasonic))) and	US-PGPUB;	13:45
		(hermetically or sealed)	EPO; JPO;	10.13
		(Nermeneally or sealed)	DERWENT	
	10914	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
	10314	205/88,98,122,123,125,148,157,183,184,187,261,291.cc		14:07
		427/96,98,443.1.ccls.	EPO; JPO;	14.07
	,	427/90,90,443.1.0015.	DERWENT	
	1933	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
-	1933 .			14:07
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc	EPO; JPO;	14.07.
		427/96,98,443.1.ccls.) and semiconductor	DERWENT	
		(/204/100 212 222 242 272 275 1 -		2002/04/20
-	506	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT; US-PGPUB;	2003/04/30
- 1				14:07
	ar.	205/88,98,122,123,125,148,157,183,184,187,261,291.cc	Í	
	125	427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	2002/04/20
-	135	(((20)4d)(1998,212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
	·	204/224r.ccls.	US-PGPUB;	14:08`
*		205/88,98,122,123,125,148,157,183,184,187,261,291.cc	1	,
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or	LICRATE	2002 (04/20
-	61	(((((RQ4/b98))212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:11
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		24
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or	LICD 4.T	2002 (04)(20
-	18	((((RO4(b9B')))12h2 3(a)24a)27a;27ta;trad)s.	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:12
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or		
	2	(((((20.44b98))))12n2 320B42 27730B3511.octs:asnfer)	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:12
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc	l .	
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or		